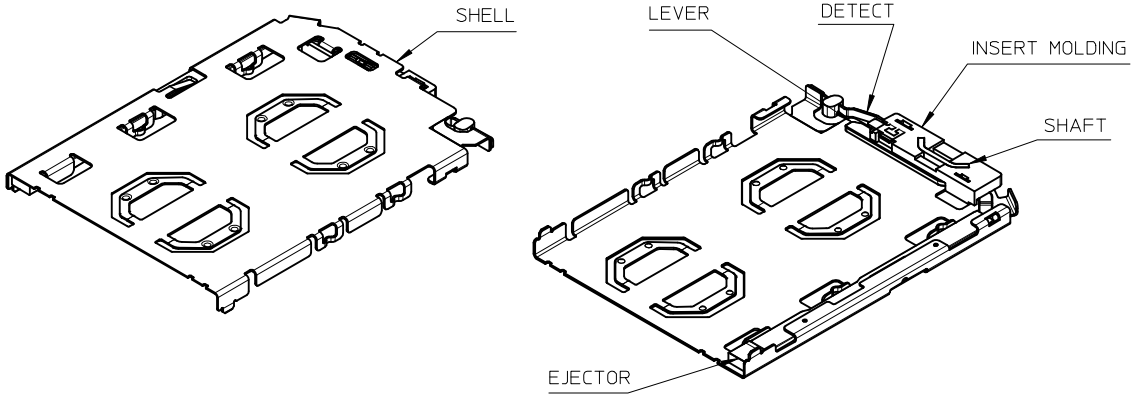
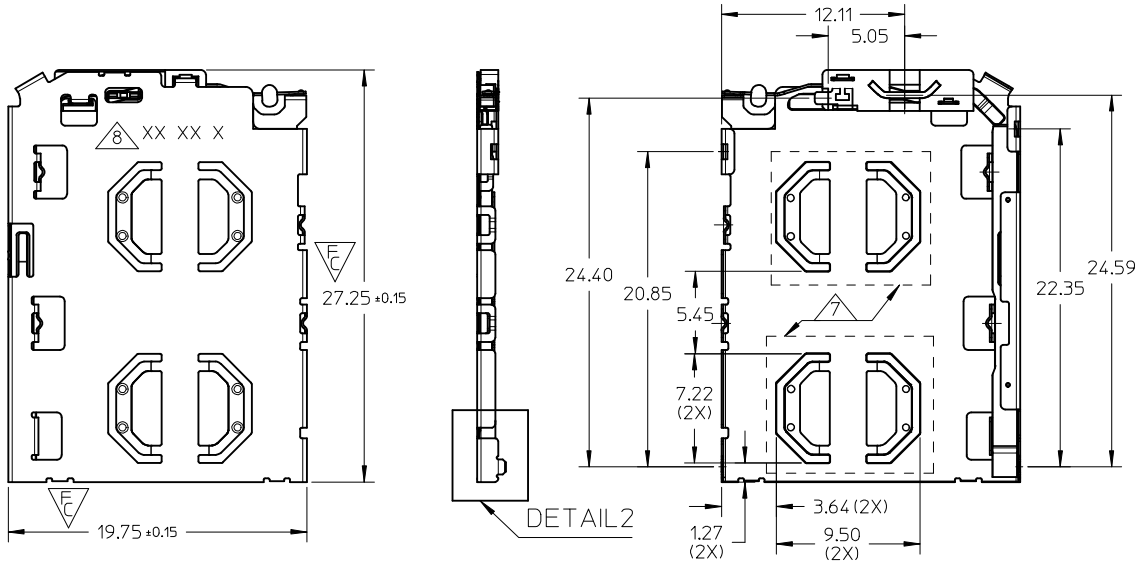
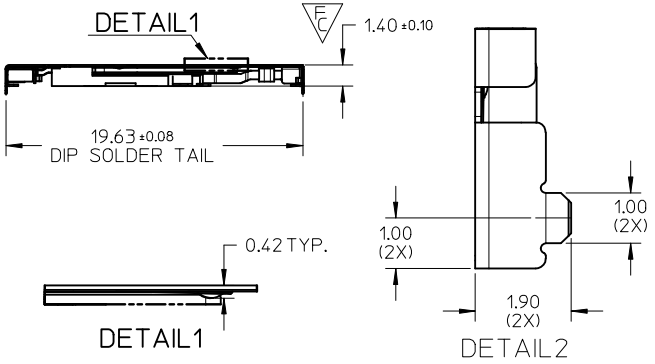
THIS DESIGN IS BASED ON DESIGN OBJECTIVES AND IS STRICTLY TENTATIVE. IT MAY CHANGE BASED ON RESULTS OF ADDITIONAL DESIGN REVIEWS & VERIFICATIONS.





NOTES:
1. MATERIALS:
INSERT MOLD HOUSING: LCP, UL94V-0;
LEVER, SHAFT , EJECTOR , SHELL: STAINLESS STEEL;
DETECT SPRING: COPPER ALLOY;
2. FINISHES:
DETECT SPRING:
1.27um MIN. NICKEL UNDERPLATING OVERALL;
0.127um MIN. GOLD PLATING ON CONTACT AREA;
1.27 um MIN. TIN PLATING ON SOLDERING TAIL;
SHELL:
1.27um MIN NICKEL UNDERPLATING OVERALL;
0.025um MIN GOLD PLATING ON CONTACT AREA AND SOLDERING AREA;
SHAFT: 1.27um MIN TIN ON SOLDERING TAIL;
3. PRODUCT SPECIFICATION: PS-151031-001;
4. PACKAGING SPECIFICATION: PK-151031-001;PK-151032-001
5. SOLDER TAIL COPLANARITY: 0.10 MM MAX BEFORE REFLOW
6. THIS PART IS A FRAME ONLY, IT SHOULD BE USED TOGETHER WITH 0.35MM BLOCK SIM 151032 FOR AN ENTIRE SIM POP OUT SYSTEM;
7. 0.10 MINIMUM KEEP OUT ZONE FROM TOP SURFACE OF SHELL DURING INSERTION AND WITHDRAWAL OF TRAY (WITH SIM CARD)
8. DATE CODE PRINTED: XX XX X
DAY
WEEK
YEAR



REV	DESCRIPTION
7	CHANGE BLOCK SIM AND TRAY EC NO: S2014-0434 2013/11/04 DRWN:JZENG 2014/01/02 CH'KD:JTAN02 2014/01/27 APPR:KHLIM

QUALITY SYMBOLS
FA=0
FC=4
FB=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.20	± ---
1 PLACE	± 0.20	± ---
0 PLACE	± ---	± ---

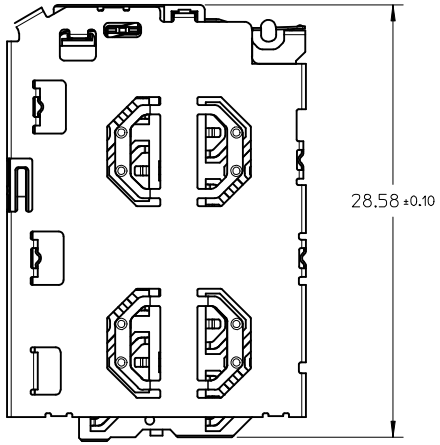
ANGULAR ± 3 °

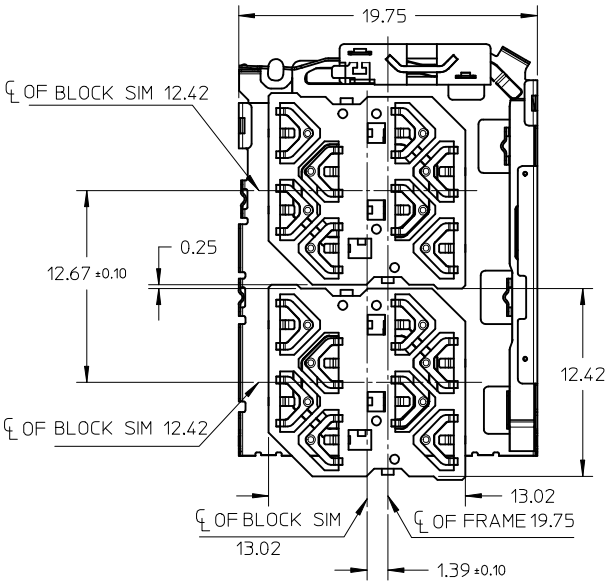
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE	MM ONLY
SCALE	NTS
DESIGN UNITS	METRIC
	THIRD ANGLE PROJECTION
DRAWN BY / DATE	JZENG 2013/11/04
CHECKED BY / DATE	JTAN02 2013/12/05
APPROVED BY / DATE	KHLIM 2014/01/27
MATERIAL NO.	1510310001
TITLE	DUAL MICRO SIM FRAME 1.40 H
DOCUMENT NO.	SD-151031-0001
SHEET NO.	1 OF 5
SIZE	A3

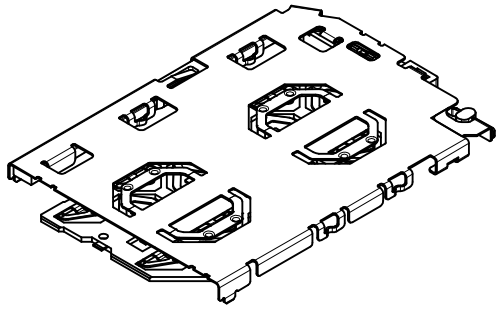
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

SIM CONNECTOR
(WITH 151032 BLOCK SIM CONNECTOR)

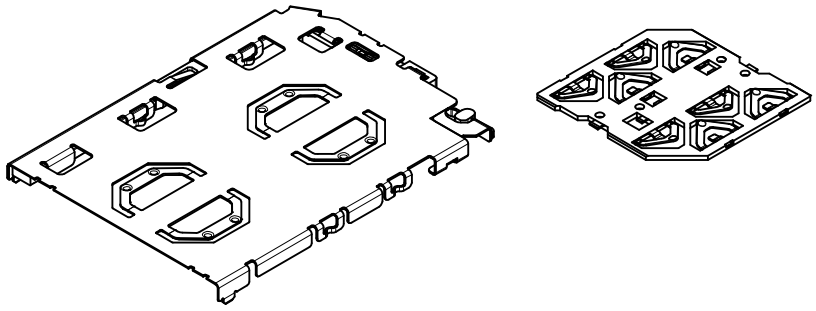




SIM CONNECTOR BOM



FRAME + BLOCK SIM



151032 SERIES

151031 SERIES

THIS DESIGN IS BASED ON DESIGN OBJECTIVES AND IS STRICTLY TENTATIVE. IT MAY CHANGE BASED ON RESULTS OF ADDITIONAL DESIGN REVIEWS & VERIFICATIONS.

SEE SHEET1	DESCRIPTION	2013/11/04	
EC NO: S2014-0434		2014/01/02	
DRWN:JZENG		2014/01/27	
CH'KD:JTAN02			
APPR:KHLIM			
7	REV		

QUALITY SYMBOLS
FA=0
FC=0
FV=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

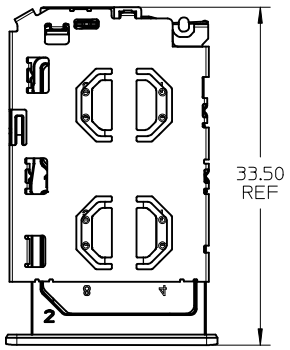
	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.20	± ---
1 PLACE	± 0.20	± ---
0 PLACE	± ---	± ---
ANGULAR ± 3 °		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

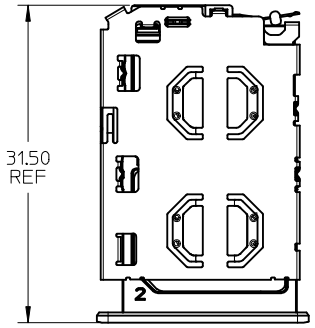
DIMENSION STYLE: MM ONLY	SCALE: NTS	DESIGN UNITS: METRIC	THIRD ANGLE PROJECTION
DRAWN BY: JZENG	DATE: 2013/11/04	TITLE: DUAL MICRO SIM FRAME 1.40 H	
CHECKED BY: JTAN02	DATE: 2013/12/05		
APPROVED BY: KHLIM	DATE: 2014/01/27	molex	
MATERIAL NO.: 1510310001		DOCUMENT NO.: SD-151031-0001	SHEET NO.: 2 OF 5
SIZE: A3			

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

SIM CONNECTOR FRAME AND TRAY



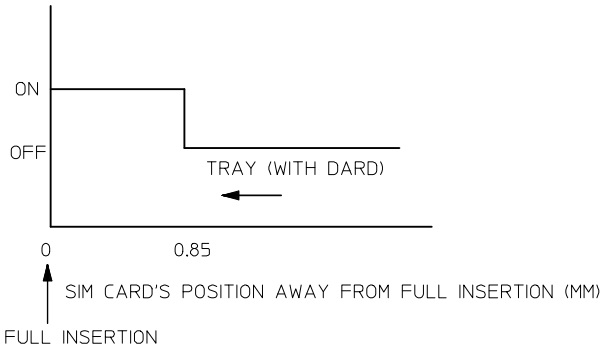
TRAY EJECTED POSITION



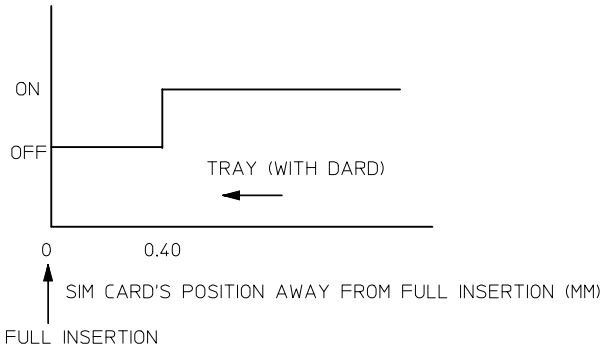
TRAY INSERTION POSITION

TRAY DETECT PIN DEFINITION	
TRAY DETECT PIN GND NORMAL SHORT (WITHOUT TRAY)	TRAY DETECT PIN AFTER TRAY INSERTED AFTER TRAY INSERTED OPEN

SIGNAL PIN



DETECT SWITCH PIN



ENTER DESCRIPTION
EC NO: S2014-0434 2013/11/04
DRWN:JZENG 2014/01/02
CH'KD:JTAN02 2014/01/27
APPR:KHLIM
DESCRIPTION
REV
7

QUALITY SYMBOLS
$\sqrt{F_A}$=0
$\sqrt{F_C}$=0
$\sqrt{F_V}$=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.20	± ---
1 PLACE	± 0.20	± ---
0 PLACE	± ---	± ---

ANGULAR ± 3 °

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

DRAWN BY: JZENG DATE: 2013/11/04
CHECKED BY: JTAN02 DATE: 2013/12/05
APPROVED BY: KHLIM DATE: 2014/01/27

TITLE: DUAL MICRO SIM FRAME 1.40 H

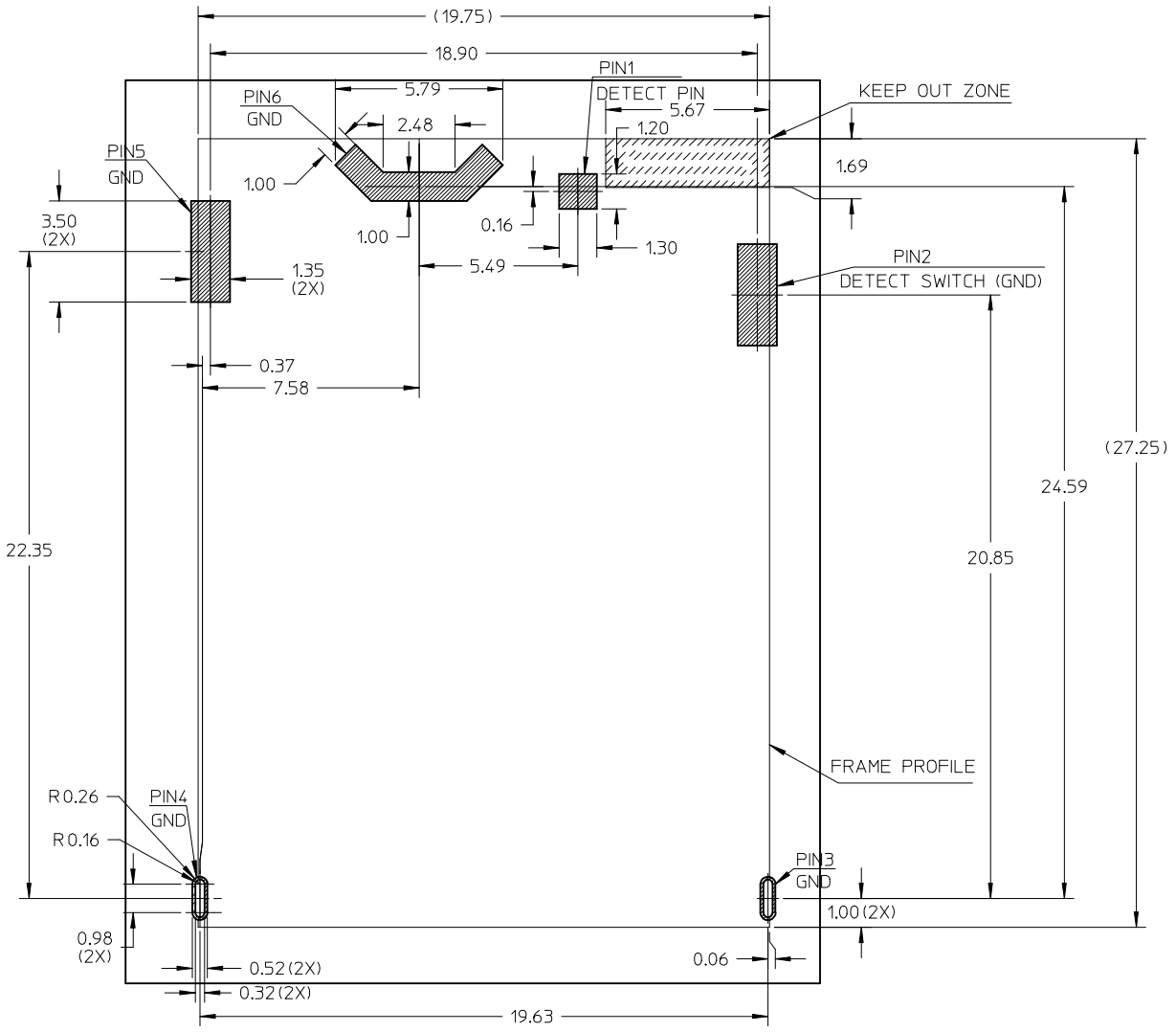
molex

MATERIAL NO.: 1510310001
DOCUMENT NO.: SD-151031-0001
SHEET NO.: 3 OF 5
SIZE: A3

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

151031 FRAME SOLDERING AREA:

KEEP OUT ZONE:



THIS DESIGN IS BASED ON DESIGN OBJECTIVES AND IS STRICTLY TENTATIVE. IT MAY CHANGE BASED ON RESULTS OF ADDITIONAL DESIGN REVIEWS & VERIFICATIONS.

RECOMMENDED PCB LAYOUT: TOLERANCE ±0.05
RECOMMENDED PCB THICKNESS: 0.80MM
RECOMMENDED STENCIL THICKNESS: 0.10MM

SEE SHEET 1
EC NO: S2014-0434 2013/11/04
DRWN:JZENG 2014/01/02
CH'KD:JTAN02 2014/01/27
APPR:KHLIM
DESCRIPTION
REV
7

QUALITY SYMBOLS
FA=0
FC=0
FP=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.20	± ---
1 PLACE	± 0.20	± ---
0 PLACE	± ---	± ---

ANGULAR ± 3 °
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: NTS
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

DRAWN BY: JZENG DATE: 2013/11/04
CHECKED BY: JTAN02 DATE: 2013/12/05
APPROVED BY: KHLIM DATE: 2014/01/27

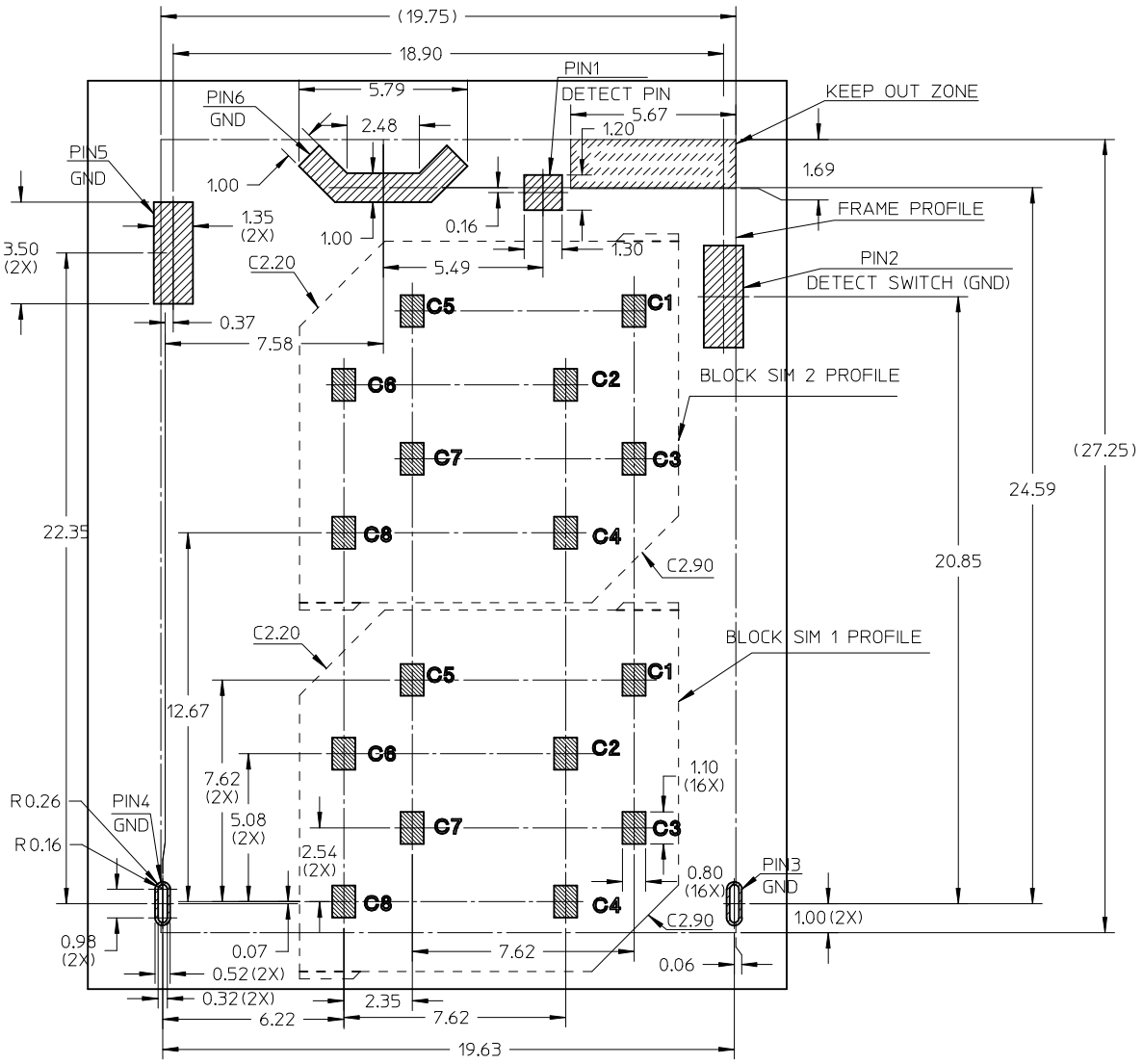
TITLE: DUAL MICRO SIM FRAME 1.40 H

molex

MATERIAL NO.: 1510310001
DOCUMENT NO.: SD-151031-0001
SHEET NO.: 4 OF 5
SIZE: A3

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

151031 FRAME SOLDERING AREA:
151032 BLOCK SIM SOLDERING AREA:
KEEP OUT ZONE:



THIS DESIGN IS BASED ON DESIGN OBJECTIVES AND IS STRICTLY TENTATIVE. IT MAY CHANGE BASED ON RESULTS OF ADDITIONAL DESIGN REVIEWS & VERIFICATIONS.

RECOMMENDED PCB LAYOUT: TOLERANCE ±0.05
RECOMMENDED PCB THICKNESS: 0.80MM
RECOMMENDED STENCIL THICKNESS: 0.10MM

SEE SHEET 1
EC NO: S2014-0434 2013/11/04
DRWN:JZENG 2014/01/02
CH'KD:JTAN02 2014/01/27
APPR:KHLIM
DESCRIPTION
REV
7

QUALITY SYMBOLS
$\sqrt{F_A}$=0
$\sqrt{F_C}$=0
$\sqrt{F_P}$=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.20	± ---
1 PLACE	± 0.20	± ---
0 PLACE	± ---	± ---

ANGULAR ± 3 °
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: NTS
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

DRAWN BY: JZENG DATE: 2013/11/04
CHECKED BY: JTAN02 DATE: 2013/12/05
APPROVED BY: KHLIM DATE: 2014/01/27

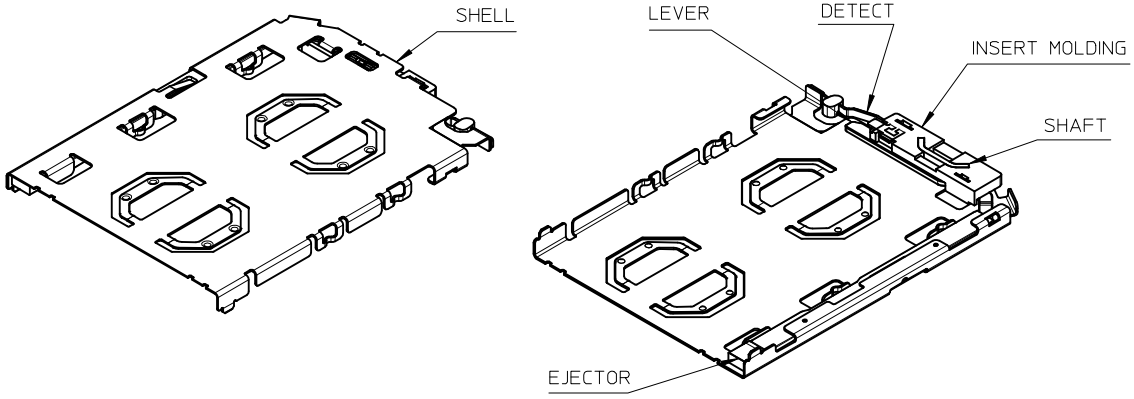
TITLE: DUAL MICRO SIM FRAME 1.40 H

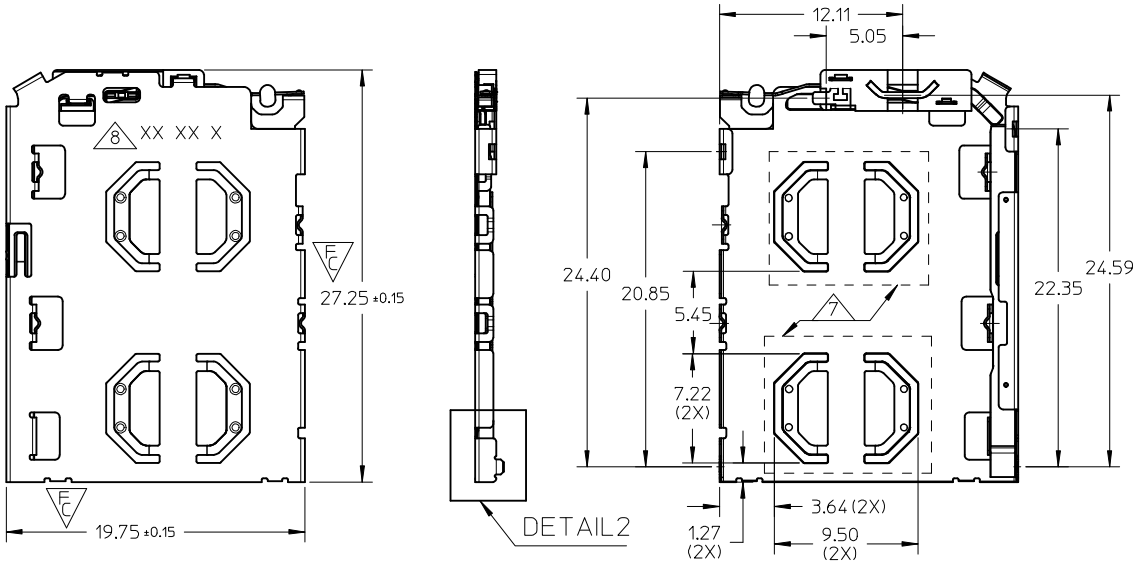
molex

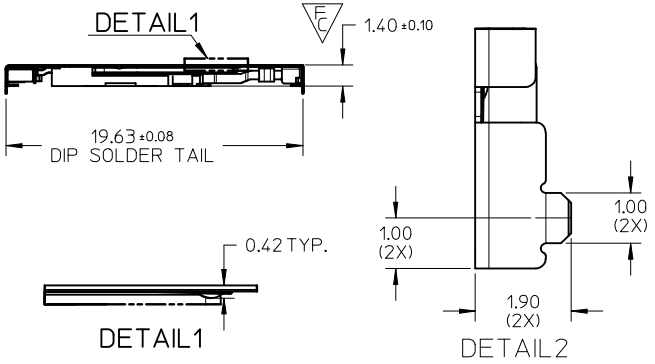
MATERIAL NO.: 1510310001
DOCUMENT NO.: SD-151031-0001
SHEET NO.: 5 OF 5
SIZE: A3

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

THIS DESIGN IS BASED ON DESIGN OBJECTIVES AND IS STRICTLY TENTATIVE. IT MAY CHANGE BASED ON RESULTS OF ADDITIONAL DESIGN REVIEWS & VERIFICATIONS.







NOTES:
1. MATERIALS:
INSERT MOLD HOUSING: LCP, UL94V-0;
LEVER, SHAFT , EJECTOR , SHELL: STAINLESS STEEL;
DETECT SPRING: COPPER ALLOY;
2. FINISHES:
DETECT SPRING:
1.27um MIN. NICKEL UNDERPLATING OVERALL;
0.127um MIN. GOLD PLATING ON CONTACT AREA;
1.27 um MIN. TIN PLATING ON SOLDERING TAIL;
SHELL:
1.27um MIN NICKEL UNDERPLATING OVERALL;
0.025um MIN GOLD PLATING ON CONTACT AREA AND SOLDERING AREA;
SHAFT: 1.27um MIN TIN ON SOLDERING TAIL;
3. PRODUCT SPECIFICATION: PS-151031-001;
4. PACKAGING SPECIFICATION: PK-151031-001;PK-151032-001
5. SOLDER TAIL COPLANARITY: 0.10 MM MAX BEFORE REFLOW
6. THIS PART IS A FRAME ONLY, IT SHOULD BE USED TOGETHER WITH 0.35MM BLOCK SIM 151032 FOR AN ENTIRE SIM POP OUT SYSTEM;
7. 0.10 MINIMUM KEEP OUT ZONE FROM TOP SURFACE OF SHELL DURING INSERTION AND WITHDRAWAL OF TRAY (WITH SIM CARD)
8. DATE CODE PRINTED: XX XX X
DAY
WEEK
YEAR

UPDATED DRAWING
EC NO: S2014-0434 2013/12/13
DRWN:JZENG 2014/01/02
CH'KD:JTANO2 2014/01/27
APPR:KHLIM
DESCRIPTION
REV: 3

QUALITY SYMBOLS
FA=0
FC=4
FB=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.20	± ---
1 PLACE	± 0.20	± ---
0 PLACE	± ---	± ---

ANGULAR ± 3 °
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: NTS
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

DRAWN BY: JZENG DATE: 2013/12/13
CHECKED BY: DATE:
APPROVED BY: KHLIM DATE: 2014/01/27

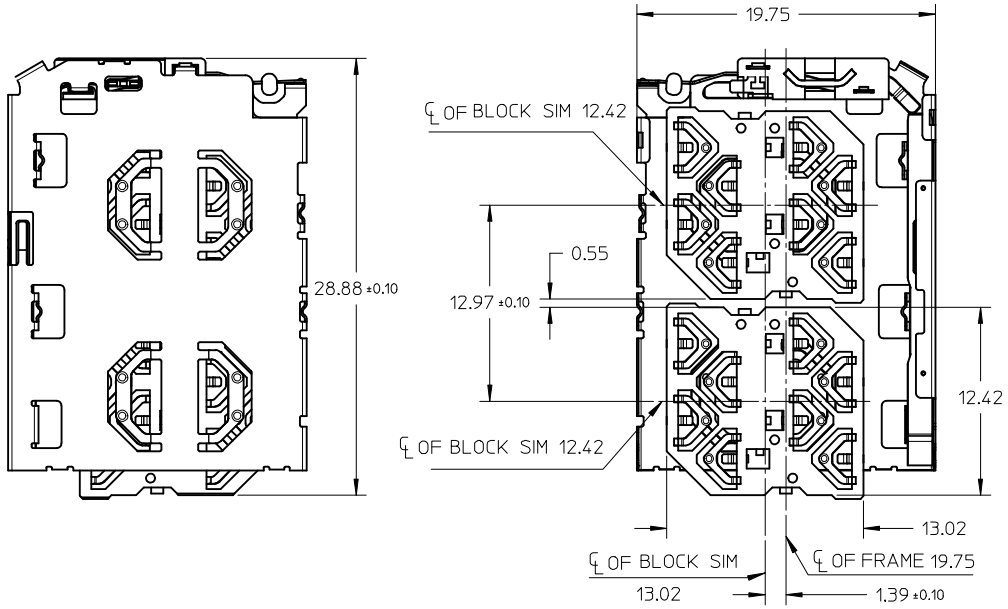
TITLE: DUAL MICRO SIM FRAME 1.40H

molex

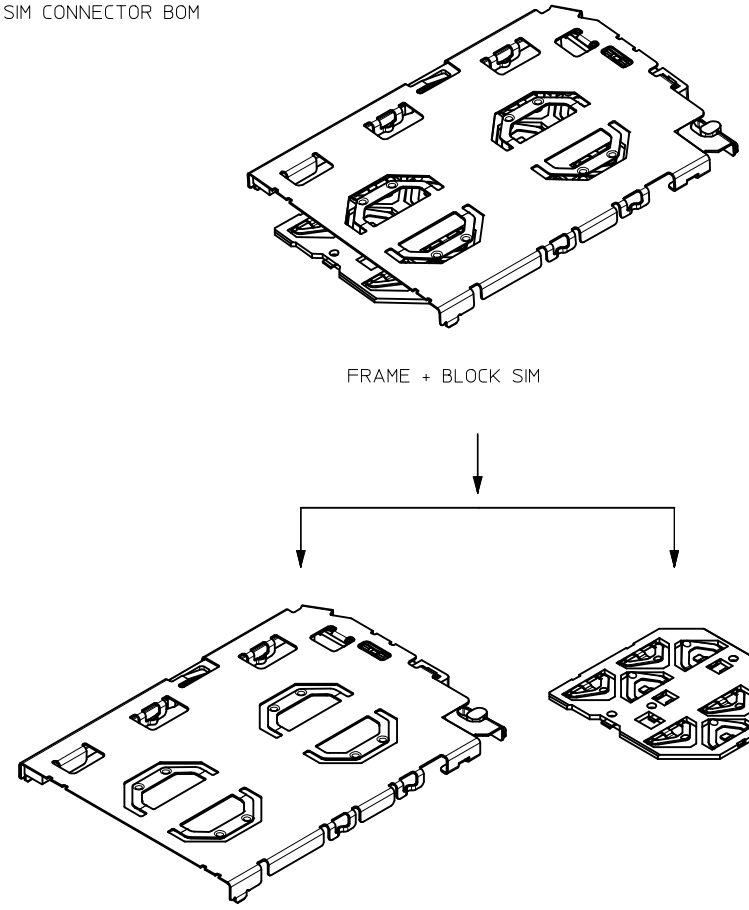
MATERIAL NO.: 1510310001
DOCUMENT NO.: SD-151031-0002
SHEET NO.: 1 OF 4
SIZE: A3

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

SIM CONNECTOR
(WITH 151032 BLOCK SIM CONNECTOR)



SIM CONNECTOR BOM



THIS DESIGN IS BASED ON DESIGN OBJECTIVES AND IS STRICTLY TENTATIVE. IT MAY CHANGE BASED ON RESULTS OF ADDITIONAL DESIGN REVIEWS & VERIFICATIONS.

SEE SHEET1
EC NO: S2014-0434
DRWN:JZENG 2013/12/13
CH'KD:JTANG2 2014/01/02
APPR:KHLIM 2014/01/27
REV: 3
DESCRIPTION

QUALITY SYMBOLS
FA=0
FC=0
FP=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.20	± ---
1 PLACE	± 0.20	± ---
0 PLACE	± ---	± ---

ANGULAR ± 3 °
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: NTS
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

DRAWN BY: JZENG DATE: 2013/12/13
CHECKED BY: DATE:
APPROVED BY: KHLIM DATE: 2014/01/27

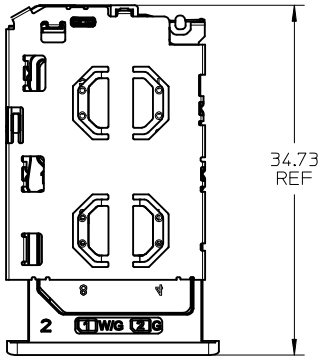
TITLE: DUAL MICRO SIM FRAME 1.40H

molex

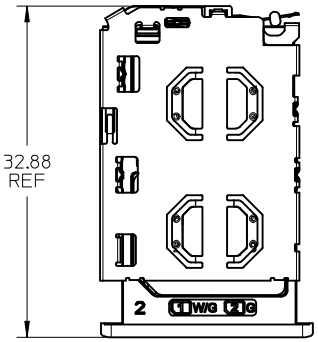
MATERIAL NO.: 1510310001
DOCUMENT NO.: SD-151031-0002
SHEET NO.: 2 OF 4
SIZE: A3

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

SIM CONNECTOR FRAME AND TRAY

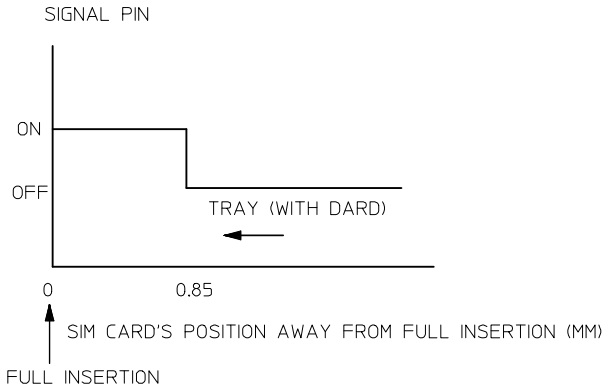


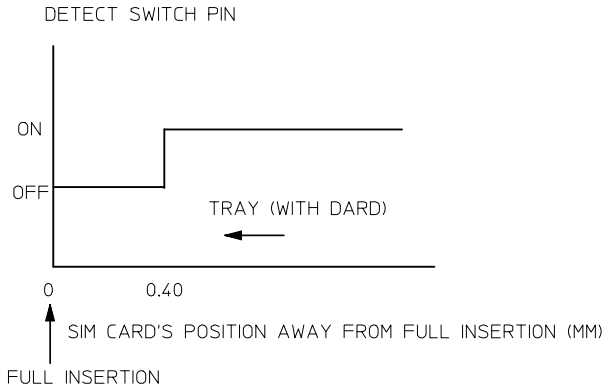
TRAY EJECTED POSITION



TRAY INSERTION POSITION

TRAY DETECT PIN DEFINITION	
TRAY DETECT PIN GND NORMAL SHORT (WITHOUT TRAY)	TRAY DETECT PIN AFTER TRAY INSERTED AFTER TRAY INSERTED OPEN





SEE SHEET 1
EC NO: S2014-0434 2013/12/13
DRWN:JZENG 2014/01/02
CH'KD:JTANG2 2014/01/27
APPR:KHLIM
DESCRIPTION
REV
3

QUALITY SYMBOLS
FA=0
FC=0
FP=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.20	± ---
1 PLACE	± 0.20	± ---
0 PLACE	± ---	± ---

ANGULAR ± 3 °

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE:
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

DRAWN BY: JZENG DATE: 2013/12/13
CHECKED BY: DATE:
APPROVED BY: KHLIM DATE: 2014/01/27

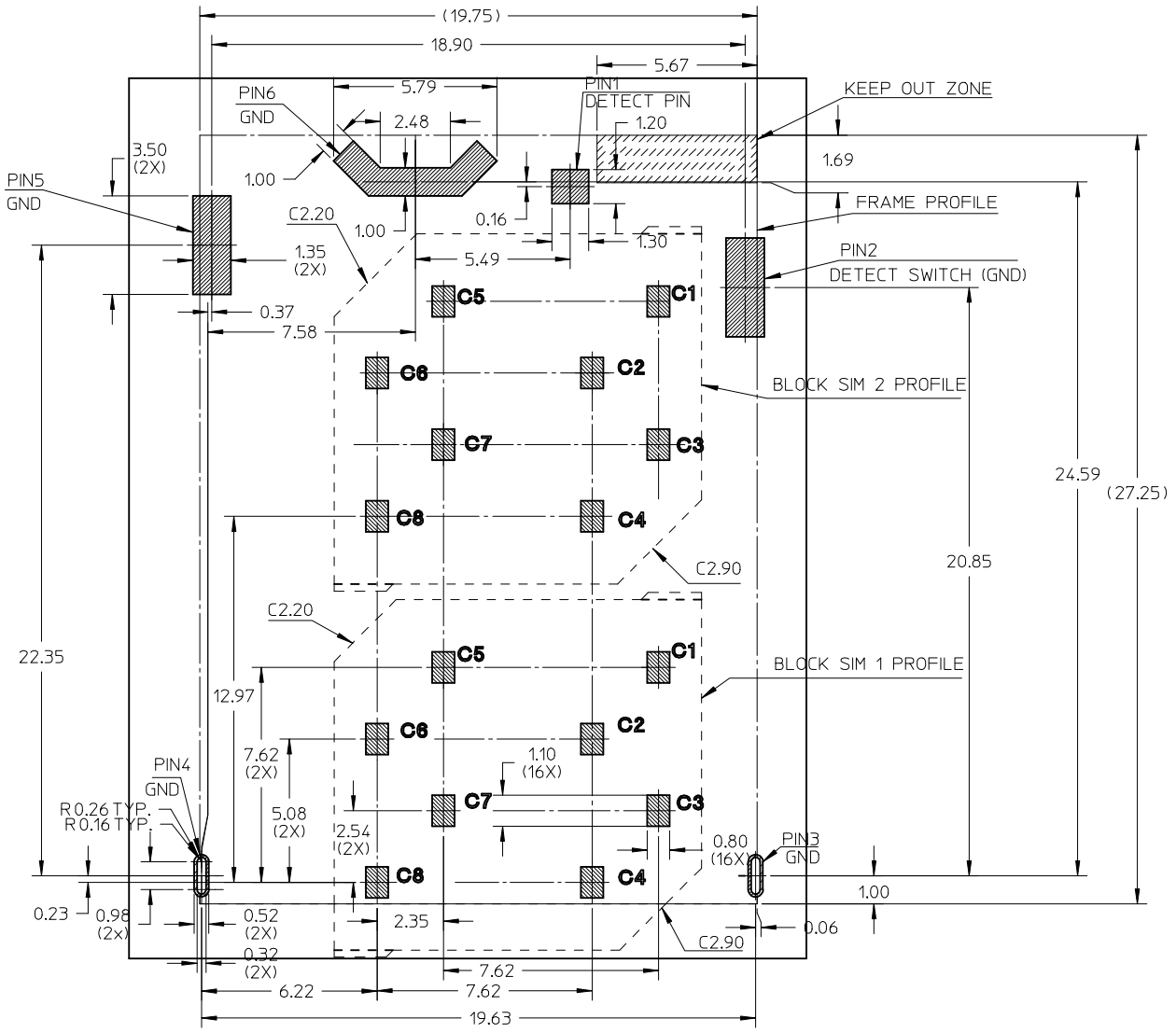
TITLE: DUAL MICRO SIM FRAME 1.40H

molex

MATERIAL NO.: 1510310001
DOCUMENT NO.: SD-151031-0002
SHEET NO.: 3 OF 4
SIZE: A3

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

151031 FRAME SOLDERING AREA:
151032 BLOCK SIM SOLDERING AREA:
KEEP OUT ZONE:



THIS DESIGN IS BASED ON DESIGN OBJECTIVES AND IS STRICTLY TENTATIVE. IT MAY CHANGE BASED ON RESULTS OF ADDITIONAL DESIGN REVIEWS & VERIFICATIONS.

RECOMMENDED PCB LAYOUT: TOLERANCE ±0.05
RECOMMENDED PCB THICKNESS: 0.80MM
RECOMMENDED STENCIL THICKNESS: 0.10MM

SEE SHEET 1
EC NO: S2014-0434 2013/12/13
DRWN:JZENG 2014/01/02
CH'KD:JTANO2 2014/01/27
APPR:KHLIM
DESCRIPTION
REV
3

QUALITY SYMBOLS
$\sqrt{F_A}$=0
$\sqrt{F_C}$=0
$\sqrt{F_P}$=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.20	± ---
1 PLACE	± 0.20	± ---
0 PLACE	± ---	± ---

ANGULAR ± 3 °
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: NTS
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

DRAWN BY: JZENG DATE: 2013/12/13
CHECKED BY: DATE:
APPROVED BY: KHLIM DATE: 2014/01/27

TITLE: DUAL MICRO SIM FRAME 1.40H

molex

MATERIAL NO.: 1510310001
DOCUMENT NO.: SD-151031-0002
SHEET NO.: 4 OF 4
SIZE: A3

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гарантия бесперебойности производства и качества выпускаемой продукции

О компании

ООО "ТрейдЭлектроникс" - это оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов. Реализуемая нашей компанией продукция насчитывает более полумиллиона наименований.

Благодаря этому наша компания предлагает к поставке практически не ограниченный ассортимент компонентов как оптовыми, мелкооптовыми партиями, так и в розницу.

Наличие собственной эффективной системы логистики обеспечивает надежную поставку продукции по конкурентным ценам в точно указанные сроки.

Срок поставки со стоков в **Европе и Америке – от 3 до 14 дней.**

Срок поставки из **Азии – от 10 дней.**

Благодаря развитой сети поставщиков, помогаем в поиске и приобретении экзотичных или снятых с производства компонентов.

Предоставляем спец цены на элементы для создания инженерных сэмплов.

Упорный труд, качественный результат дают нам право быть уверенными в себе и надежными для наших клиентов.

Наша компания это:

- Гарантия качества поставляемой продукции
- Широкий ассортимент
- Минимальные сроки поставок
- Техническая поддержка
- Подбор комплектации
- Индивидуальный подход
- Гибкое ценообразование

Наша организация особенно сильна в поставках модулей, микросхем, пассивных компонентов, ксайленсах (XC), EPF, EPM и силовой электроники.

Большой выбор предлагаемой продукции, различные виды оплаты и доставки, позволят Вам сэкономить время и получить максимум выгоды от сотрудничества с нами!

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Перечень производителей, продукцию которых мы поставляем на российский рынок



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С удовольствием будем прорабатывать для Вас поставки всех необходимых компонентов по текущим запросам для скорейшего выявления групп элементов, по которым сотрудничество именно с нашей компанией будет для Вас максимально выгодным!

С уважением,

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